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SMR/543 - 10

EXPERIMENTAL WORKSHOP ON
 HIGH TEMPERATURE SUPERCONDUCTORS AND RELATED MATERIALS
 (BASIC ACTIVITIES)

(11 February - 1 March 1991)

" High Temperature Superconducting Thin Films and Their Applications "

PART I

presented by:

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HIGH TEMPERATURE SUPERCONDUCTING THIN FILMS AND THEIR APPLICATIONS

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 DK-2800 LYNGBY, DENMARK.

3 LECTURES

- 1) THIN FILMS
- 2) JOSEPHSON JUNCTIONS
- 3) APPLICATIONS

I MAKE REFERENCE TO LOW T_c TO PUT IN PERSPECTIVE.

Low T_c

Tin \rightarrow Lead \rightarrow Niobium \rightarrow Niobium nitride

$\xi \sim 500 - 1000 \text{ \AA}$

Niobium is a getter for oxygen
it took many years to get good junctions

now: Niobium based thin film electronics

high T_c

$\xi \sim 5 - 30 \text{ \AA}$

materials problems

???

1. ... n. 2

PRESENTATION OF LABORATORY.
(PHYSICS LABORATORY I)

Low T_c	high T_c
since 1970	since 1987.
thin films. Niobium technology	thin films YBCO, BSCCO
Josephson junctions	\downarrow
Superconducting circuits	to come
samplers	
mixers	
paramps	
SQUIDS	

HTS thin film fabrication

Materials

- YBCO
- BSCCO
- TBCCO

Substrates

-
-
-

Fabrication methods

- sputtering
- laser deposition
- e-beam co evaporation
- effusion cells — " —
- MOCVD

ESTEC CONTRACT No. 8007/88/NL/PB(SC)

March 1990

HIGH TEMPERATURE SUPERCONDUCTORS: ASSESSMENT STUDY FOR SPACEBORNE SENSORS APPLICATIONS.

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EUROPEAN SPACE AGENCY CONTRACT REPORT.

The work described in this report was done under ESA contract. Responsibility for the contents resides in the author or organisation that prepared it.

MATERIALS

General Requirements for Thin Films and Multilayers

PHYSICAL/GEOMETRICAL:

- * Formation at lowest possible processing temperature (preferably near room temperature - for lift-off patterning)
- * Minimal interdiffusion at interfaces
- * Adhesion to substrate
- * Thermal compatibility with substrate (comparable thermal expansion coefficients)
- * Surface smoothness (1 to 10 nm)
- * Large, uniform area, e.g. on a 7.5 to 10 cm diameter wafer
- * Chemically passive or protected/passivated surface
- * Phase purity
- * Epitaxial compatibility with substrates (epi-films)
- * Controllable orientation, low defect concentration, no grain boundaries (epi-films)

ELECTRICAL:

- * Critical temperature: $T_c \geq 2T_{op}$
- * Lower critical field: $H_{c1}(T_{op}) \gg H_{op}$ (most cases)
- * Self-field critical current density: $J_c(T_{op}) > 10^6 \text{ A/cm}^2$
- * Rf surface resistance: $R_s(f_{op}, T_{op}, H_{op}) \ll 0.01 R_s(f_{op}, T_{op})$ of Cu
- * Low ϵ' and low $\tan \delta$ film substrate: $\tan \delta(f_{op}, T_{op}) < 10^{-6}$
- * Flux noise power: $S_{\Phi}(f, T_{op}) < 10^{-10} \text{ } \mu\text{V}^2 \text{ Hz}^{-1}$ at $f > 1 \text{ Hz}$ (measured in a ring specimen)
- * Depth of surface/interface T_c (Δ) degradation: $d_c \ll \lambda(T_{op})$

reference: A. Brajinski 1990

YBCO

Epitaxial C-axis films
lowest noise

best

TBCCO

very promising

BSCCO

too much flux flow noise

SUBSTRATES

	Crystal System	Structure	Lattice Constants	Thermal expansion coefficient
YBCO	orthorhombic	oxygen deficient perovskite	a=3.82Å b=3.69Å c=11.68Å	10-15E-6/K
BiSrCaCuO	pseudo tetra	Bi-layered structure	a=5.4Å c=30Å, 36Å	12E-6/K
TlBaCaCuO	pseudo tetra	Bi-layered structure	a=5.4Å c=36Å	
Al ₂ O ₃	trigonal	corundum	hex axes a=4.763Å c=13.003Å	7.5-8E-6/K
MgO	cubic	NaCl	a=4.203Å	13.8E-6/K
SrTiO ₃	cubic	perovskite	a=3.905Å	10.8E-6/K
YSZ	cubic	fluorite	a=5.16Å	10E-6/K

MATERIALS
SUBSTRATES

ref. Wasa et al.

ESA report 1990
C.S. Jacobsen

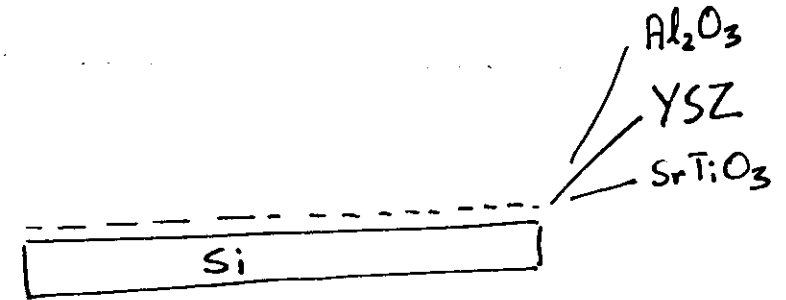
<u>Epi-Substrate</u>	SrTiO ₃	MgO	ZrO ₂ (YSZ)	LaAlO ₃
Orientation	(001)	(001)	(001)	(001)
for c ⊥ Plane	1900	9.6	25	24.5-26
ε'				
tan δ at:				
77-80K	6x10 ⁻²	4x10 ⁻⁵	7.5x10 ⁻³	8.3x10 ⁻⁵
4.2K	--	1x10 ⁻⁶	2-6x10 ⁻⁴	5x10 ⁻⁶
at f, GHz	10-1000	10-1000	10-1000	10
References	22	22,23	22	23

reference: A. Braginsky 1990.

BUFFER - LAYER.

To prevent interdiffusion at high temperatures.

Example.



TYPICAL

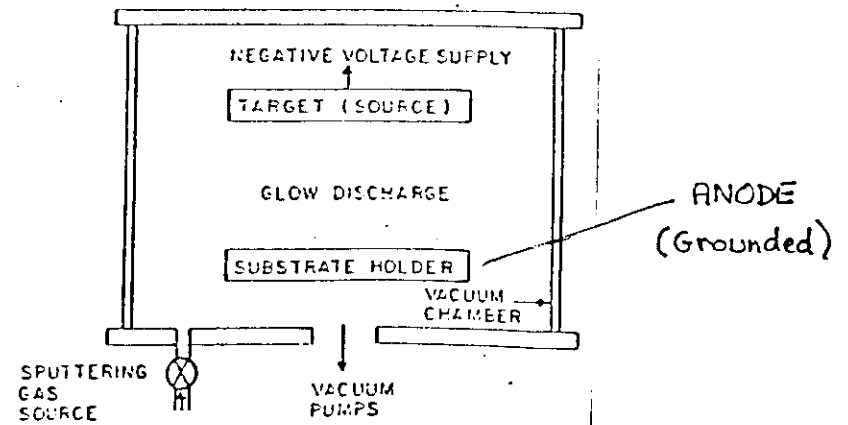
YSZ (Y₂O₃) on Si

SrTiO₃ on Al₂O₃

SPUTTERING

- dc sputtering : conducting target
- rf sputtering : insulating target possible
- YBCO : often dc sputtering
- Bi-materials : rf-sputtering

FABRICATION PROCESSES.



possibly Magnetron Sputtering (concentrate plasma)

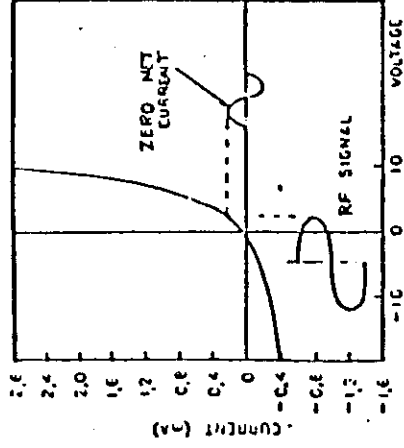
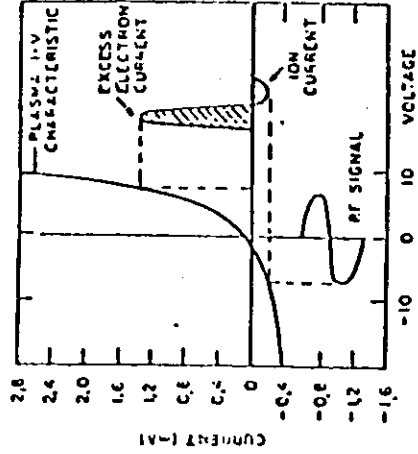
background pressure : $\sim 10^{-6}$ mbar

sputter gas (argon) : $\sim 10^{-3}$ mbar or higher

ions in the plasma bombards target and eject material to substrate

RF - sputtering

Electrical characteristics of glow discharge.



plasma IV curve :

Target obtains negative selfbias. (necessary to have ions bombard target) due to zero net current.

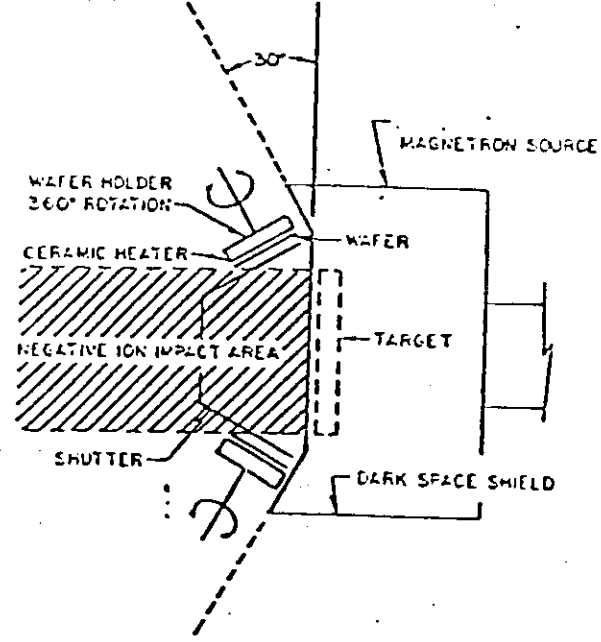
ESA report 1990

C.S. Jacobsen

OFF-AXIS SPUTTERING

(to minimize oxygen resputtering)

high sputtergas pressure (~0.5 torr)
thermalise oxygen



Substrate is placed outside the main stream of oxygen atoms.

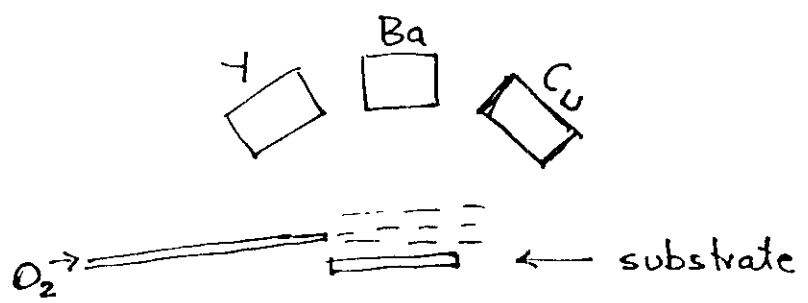
Stoichiometry preserved.

ESA report 1990

C.S. Jacobsen

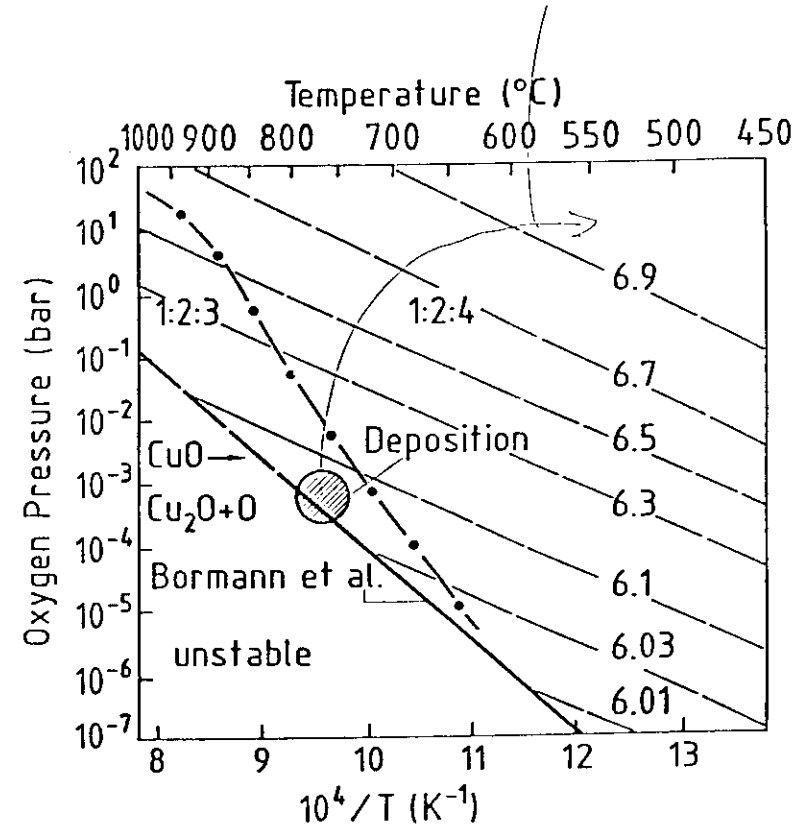
SPUTTERING .

Multiple target system.



possibility of oxygen injection (bleeding)

cylindrical targets



Cook et al. 1990 (Karlsruhe)

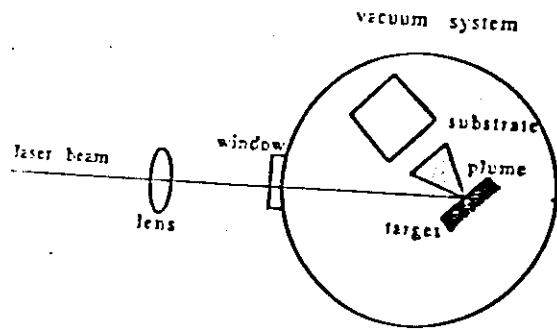
LASER DEPOSITION

Stoichiometry preserved.

details of process complicated.

(clusters, small explosions, plasma $\sim 10^4$ K...)

moderate vacuum.



Lasers: excimer laser
 Nd-YAG

ArF	193 nm
KrF	248 nm
XeCl	308 nm

pulsed operation: 5-30 ns
 10-100 MW
 1-10 Hz

energy density per pulse: 1-5 J/cm²

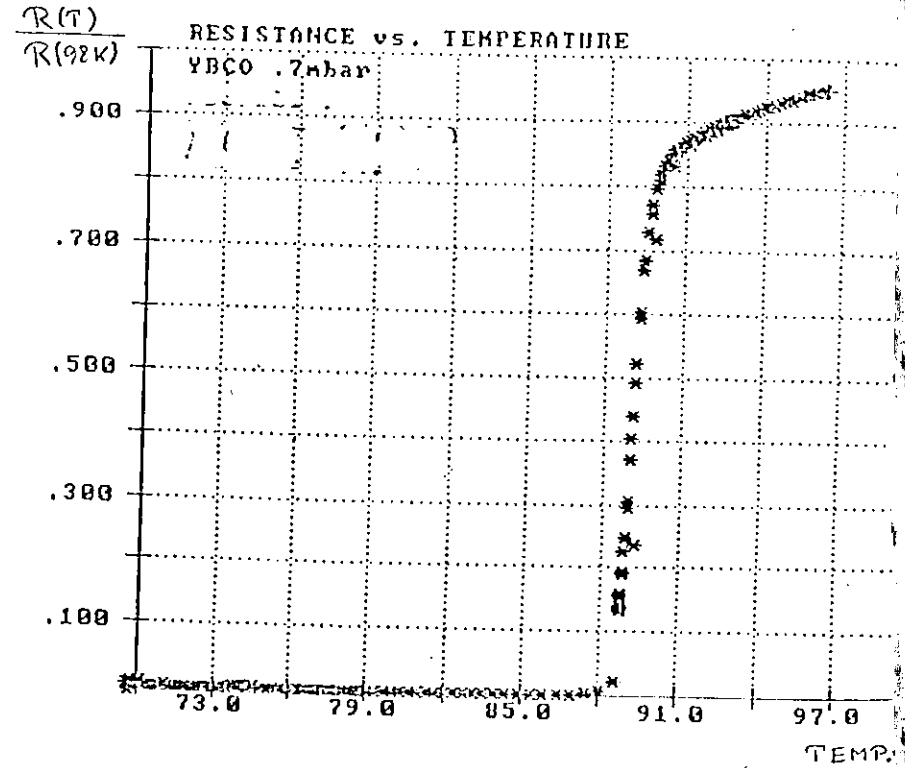


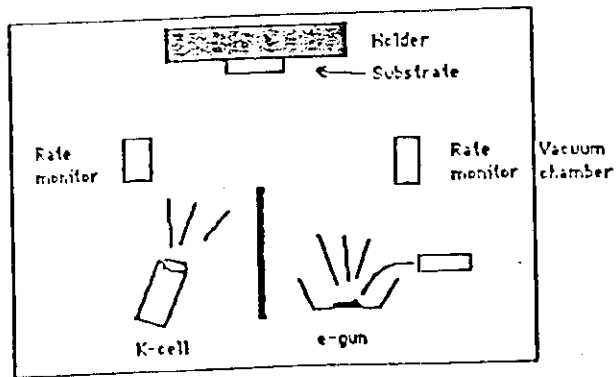
Fig. 3.8 Resistive transition in a laser deposited YBCO thin film (on (100) MgO) from NKT A/S. $T_{c0} = 87$ K.

ESA-report 1990: C.S. Jacobsen.

CO-EVAPORATED FILMS (E-GUN or EFFUSION CELL.)

High VACUUM

Very good process control?



MBE: Deposition of single layer at a time.

ESA Report: C S Jacobsen. 1990

Oxydation

for in situ fabrication.

oxygen bleeding, differential pumping

atomic oxygen (O)

ozone (O_3)

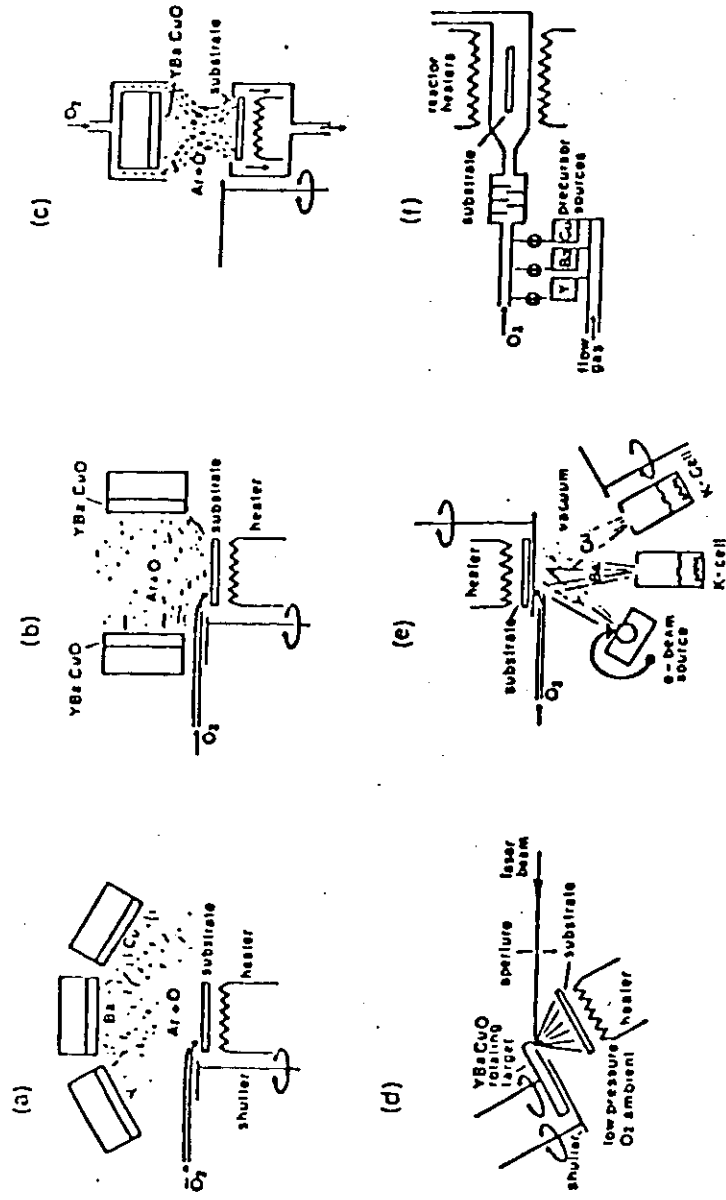


Fig. 1 Schematic diagrams showing the essential features of: (a), (b), (c) sputter deposition methods for high T_c materials; (d) laser deposition; (e) physical vapour deposition; and (f) chemical vapour deposition.

Table 3. Representative Best Properties of "As-Grown" c-Axis Epitaxial YBCO Films on SrTiO₃, MgO, ZrO₂ or LaAlO₃ Substrates.

Film grown by:	PLD	Sputtering
d, nm	10	200±100
T_c (R = 0), K	82	92
J_c (77K), A/cm ²	>10 ²	88
R_s (77K), ohm	8x10 ⁶	8x10 ⁶
at f, GHz	<7x10 ⁻³	<7x10 ⁻³
f ($R_s = \alpha R_{5Cu}$), GHz	86	86
$\alpha = 0.1$ (scaled)	73	73
$\alpha = 0.01$ (scaled)	13	13
S_{ϕ} (77K), ϕ_0^2 Hz ⁻¹	8x10 ⁻¹⁰	-
at f, Hz	1	-
References	18, 19, 20	12, 15, 21

reference: A. Braquinis 1990

THE MOST PROMISING METHODS
PRESENTLY FOR YBCO FABRICATION

AS GROWN - c-axis.

LASER DEPOSITION OFF-AXIS SPUTTERING

the target composition
deposition rate
area
pressure
deposition temperature
(77k)

	V	V
deposition rate	$\sim 100 \text{ \AA/sec}$	0.1 \AA/sec
area	$\sim 1 \text{ cm}^2$ (beam)	large (5 cm^2 wafer)
pressure	$\text{O}_2 - 200 \text{ mtorr}$	$50 - 200 \text{ mtorr (O}_2 + \text{Ar)}$
deposition temperature	$\sim 700^\circ \text{C}$	$\sim 700^\circ \text{C}$
(77k)	$5 \times 10^6 \text{ A/cm}^2$	$5 \times 10^6 \text{ A/cm}^2$

C.S. Jacobson, ESA Report 1990

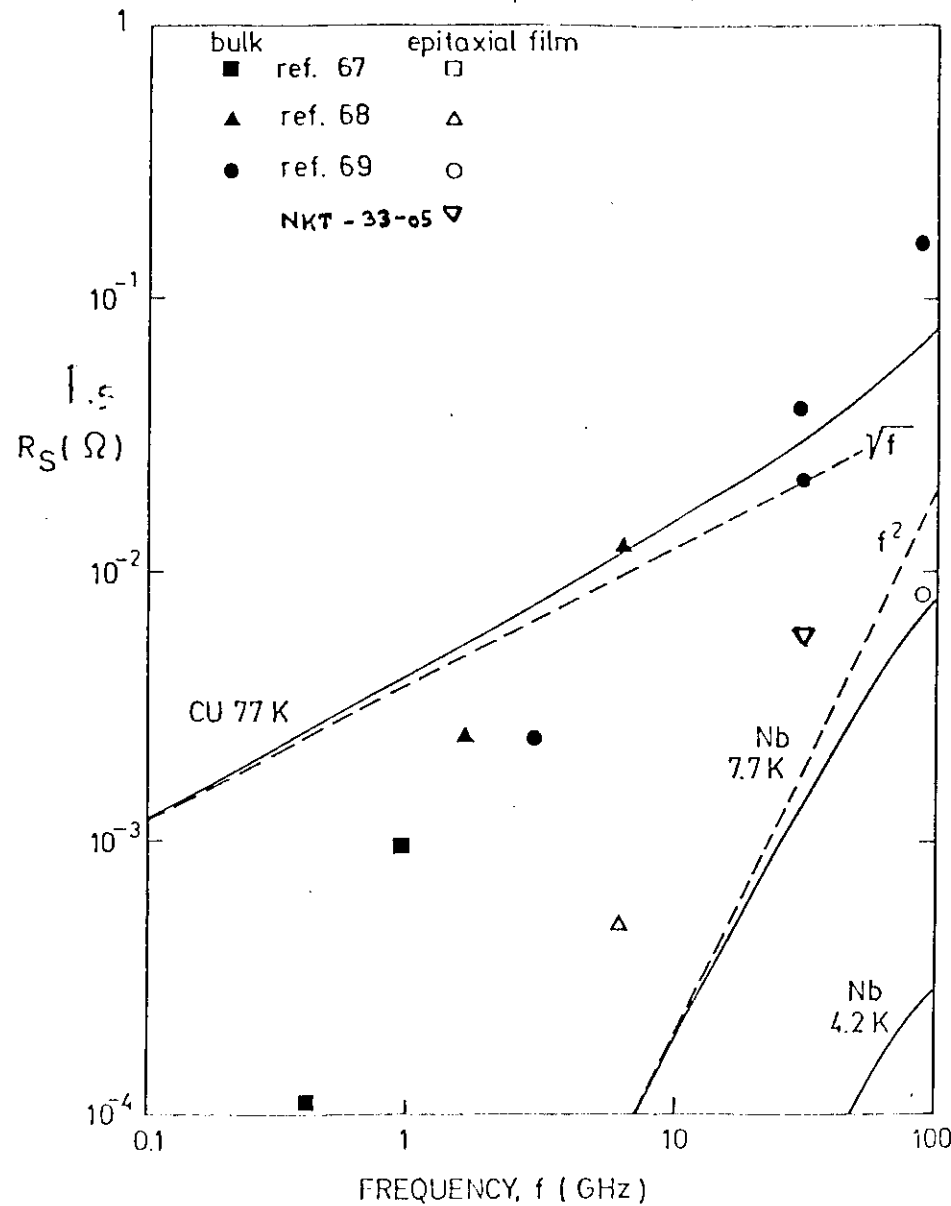
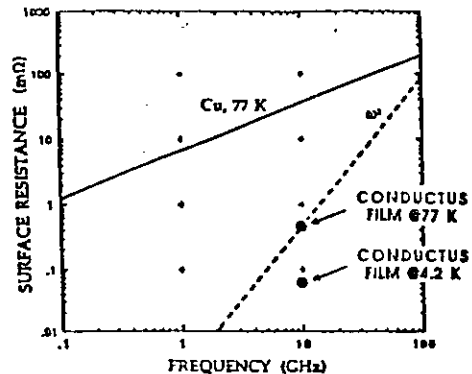


Fig. 39 Frequency dependence of the microwave surface loss, R_s , for a number of YBCO bulk and thin film samples (77 K) and copper and niobium at various temperatures.

CONDUCTUS

Superconducting Thin Films for Microwave Applications

SURFACE RESISTANCE VS. FREQUENCY



Conductus is routinely producing microwave films using the off-axis sputtering process. The results shown above illustrate significantly reduced surface losses in comparison with copper at 77 K. Such films offer the potential for improved performance of microwave resonators, filters, antennas, and other "single-layer" microwave device structures.

Films with the best properties are currently being produced on 1 cm² LaAlO₃ substrates. We can assure the following film specifications:

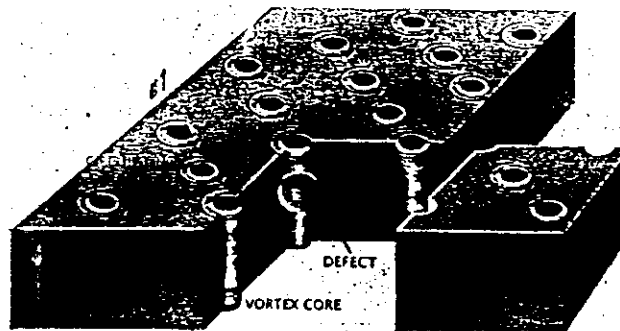
surface resistance	at 77 K:	< 2 mΩ
	at 4.2 K:	< 200 μΩ
T _c (zero resistance)	=	89.0 K
ΔT _c (10-90%)	<	1.0 K

Discuss your custom film needs with us: i.e. unusual substrate sizes or materials, patterned films and contacts.

Contact: Dr. Roger Barton at (408) 737-6700

High T_c SQUIDS.

Flux flow noise is a problem
gives large 1/f noise

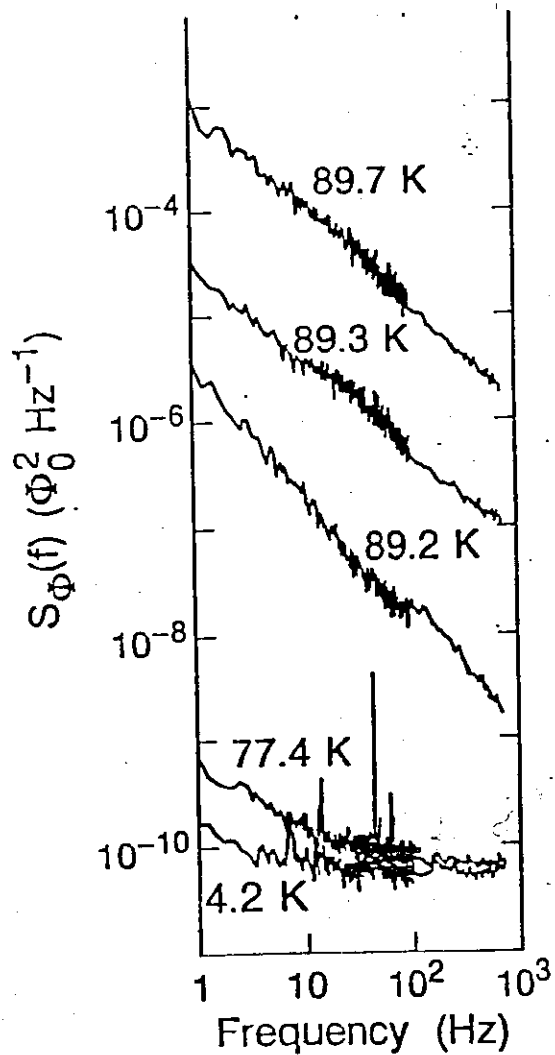


Flux lines
penetrating
film.

MAGNETIC FLUX CREEP can be diminished by introducing defects into a superconducting crystal. An external magnetic field, B, induces vortices (areas of magnetic flux surrounded by circulating current) in the crystal, which align themselves in a hexagonal matrix. A current passed through the sample pushes the vortices—the flux-creep effect—dissipating energy and so inhibiting the current. Defects in the crystal "pin" the vortices. Source: R. Bruce van Dover, AT&T Bell Laboratories.

solution ?

flux trapping / arresting
better quality films
understanding of flux motion
pancake vortices



XBL 895-5123

Ferrari et al. (1989)
 (p. 10)

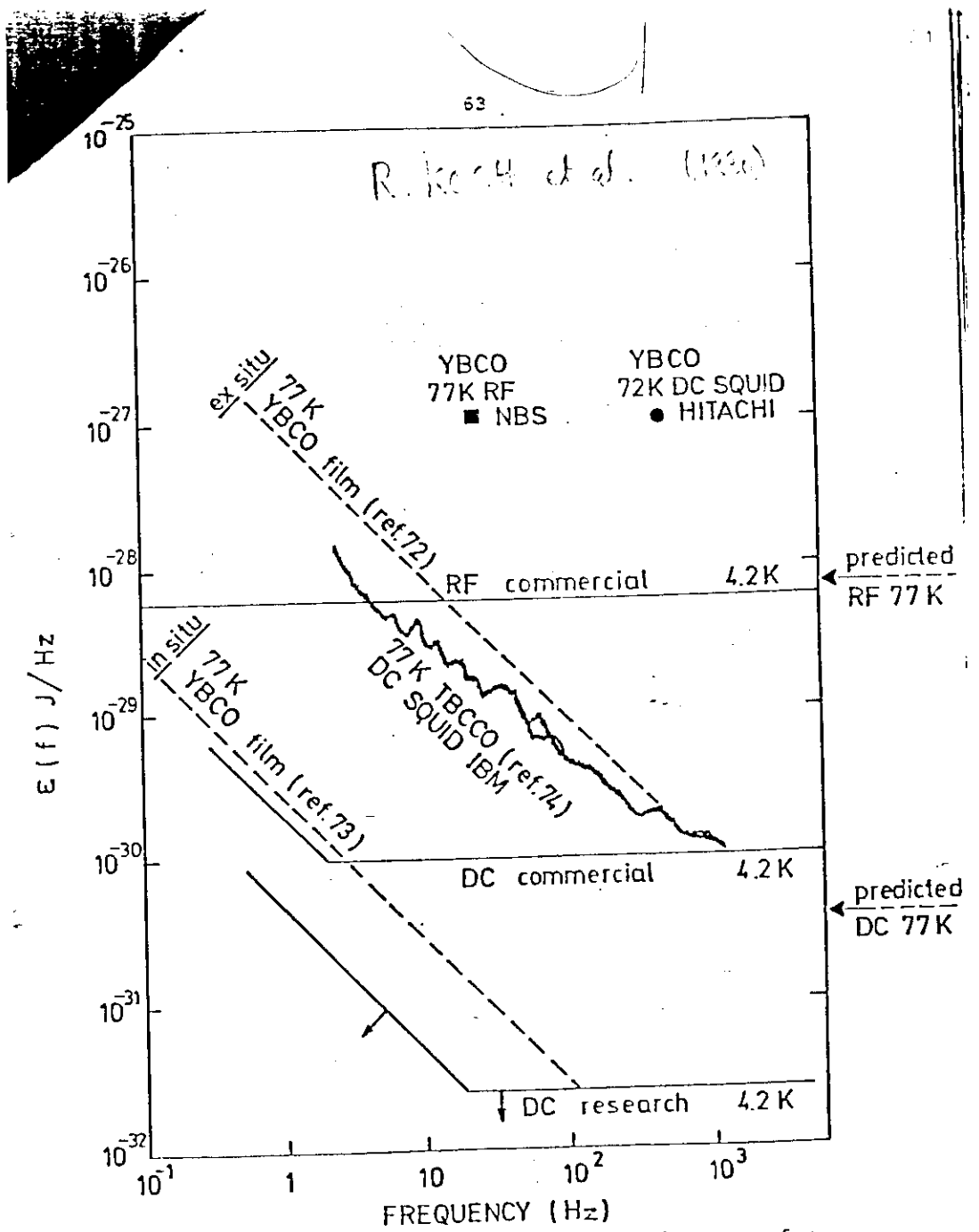


Fig. 3.9 Noise energy $E(f)/\text{Hz}$ versus frequency for several SQUID's (both low- T_c and high- T_c)

